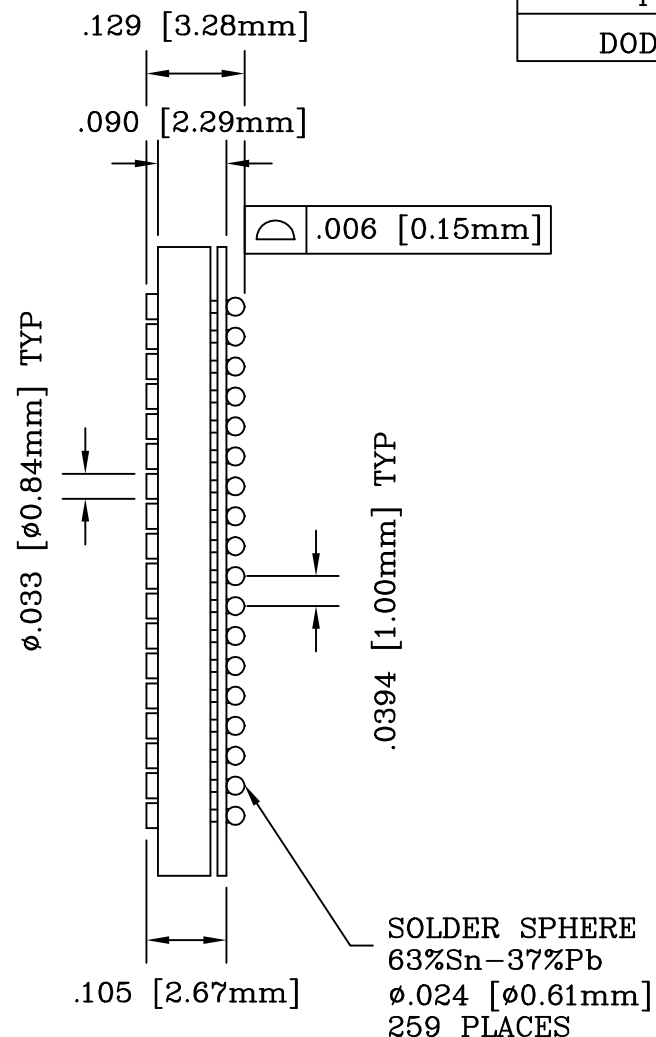
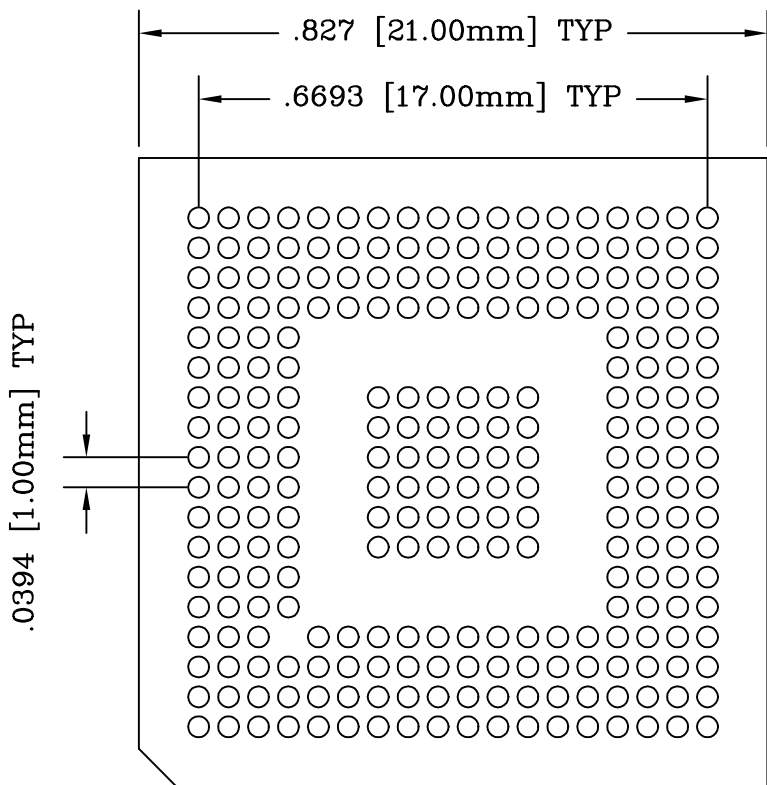


REV	DESCRIPTION	DATE	BY
A	NEW DRAWING	04/14/03	H.N.

F6754
DOD 36754



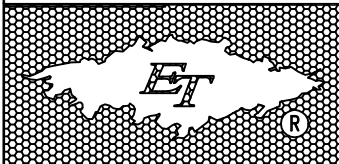
PACKAGE SPECIFICATIONS	
PIN COUNT	= 259
LEAD PITCH	= 1.00mm
GRID SIZE	= 18X18
PACKAGE SIZE	= 19.00mm

SOLDER SPHERE
63%Sn-37%Pb
ø.024 [ø0.61mm]
259 PLACES

NOTES:

- MATERIALS:**
INSULATORS: FR-4 BLACK GLASS EPOXY U.L. RATED 94V-0 (UNCLAD).
TERMINAL: BRASS, C36000, ASTM-B-16
CONTACT: BeCu, C17200, ASTM-B-194
- PLATING:**
TERMINAL: .000010 [0.000254mm] MIN. GOLD OVER
.000050 [0.00127mm] MIN. NICKEL
CONTACT: .000030 [0.000762mm] MIN. GOLD OVER
.000050 [0.00127mm] MIN. NICKEL

ALL DIMENSIONS ARE IN INCHES UNLESS OTHERWISE SPECIFIED



Emulation Technology, Inc.
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SHEET: 1 OF 1	DATE: 04/14/03	REVISION: A	ASSEMBLY DRAWING
CHECKED: Perry Munroe	DRAWN: Huy Nguyen	ITEM: BPE-259-3-018-B	DESCRIPTION: BPE-0259-3BG018-BL
Scale 4:1	DO NOT SCALE DRAWING		